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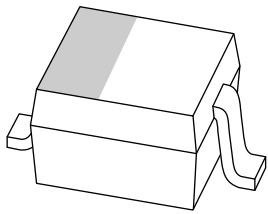
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DATA SHEET



BA591 Band-switching diode

Product specification
Supersedes data of 1998 Aug 31

2004 Feb 17



Band-switching diode

BA591

FEATURES

- Very small plastic SMD package
- Low diode capacitance: max. 1.05 pF
- Low diode forward resistance: max. 0.7 Ω
- Small inductance.

APPLICATIONS

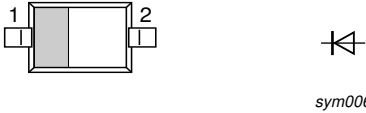
- Low loss band-switching in VHF television tuners
- Surface mount band-switching circuits.

DESCRIPTION

The BA591 is a planar, high performance band-switching diode in the very small SOD323 (SC-76) SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



sym006

Marking code: A1.
The marking bar indicates the cathode.

Fig.1 Simplified outline (SOD323; SC-76) and symbol.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BA591	–	plastic surface mounted package; 2 leads	SOD323

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	35	V
I_F	continuous forward current		–	100	mA
P_{tot}	total power dissipation	$T_s = 90\text{ }^\circ\text{C}$	–	500	mW
T_{stg}	storage temperature		–65	+150	$^\circ\text{C}$
T_j	junction temperature		–65	+150	$^\circ\text{C}$

Band-switching diode

BA591

CHARACTERISTICST_j = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	forward voltage	I _F = 10 mA	–	1	V
I _R	reverse current	V _R = 20 V	–	20	nA
C _d	diode capacitance	f = 1 MHz; note 1; see Fig.2 V _R = 1 V V _R = 3 V	0.8 0.65	1.05 0.9	pF pF
r _D	diode forward resistance	f = 100 MHz; note 1; see Fig.3 I _F = 3 mA I _F = 10 mA	0.45 0.36	0.7 0.5	Ω Ω
1/g _p	reverse resistance	V _R = 1 V; f = 100 MHz; note 1	100	–	kΩ
L _S	series inductance		2	–	nH

Note

1. Guaranteed on AQL basis; inspection level S4, AQL 1.0.

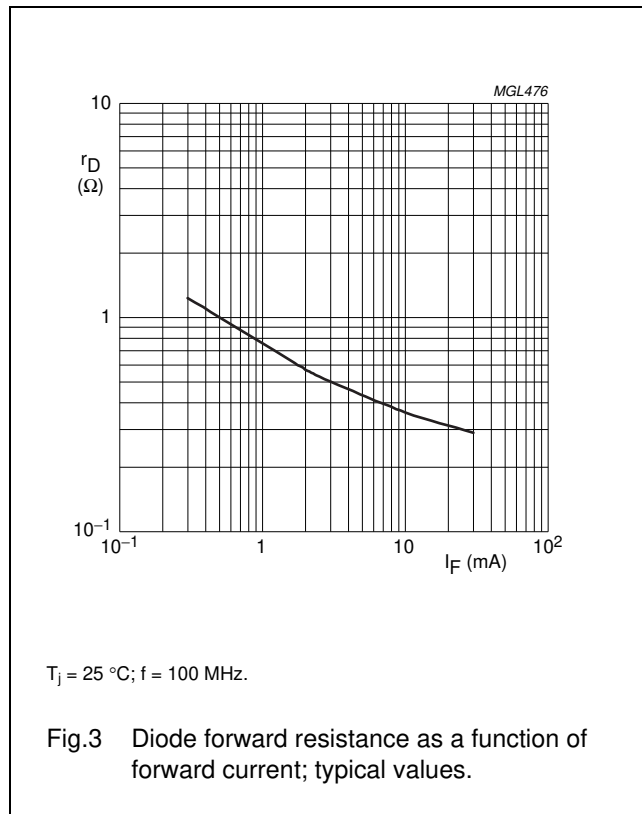
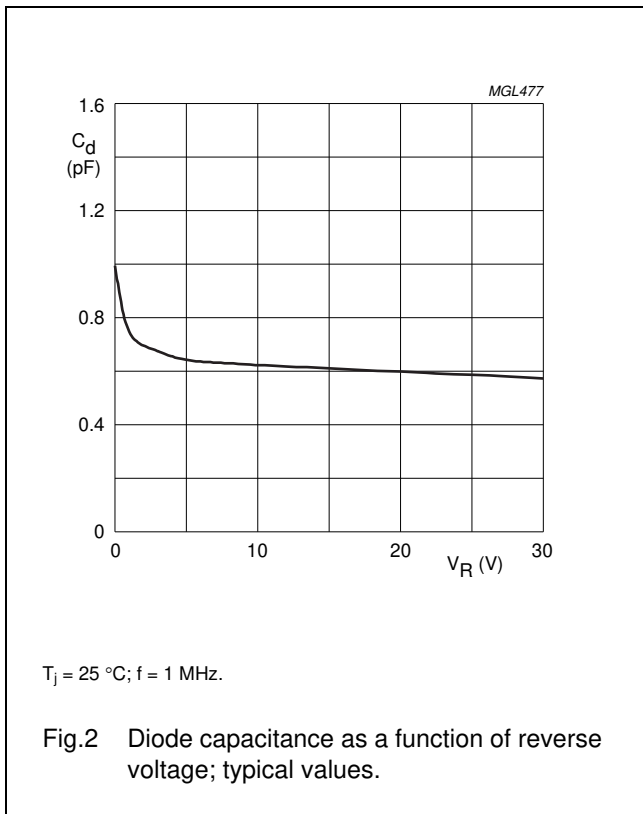
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th(j-s)}	thermal resistance from junction to soldering point	120	K/W

Band-switching diode

BA591

GRAPHICAL DATA



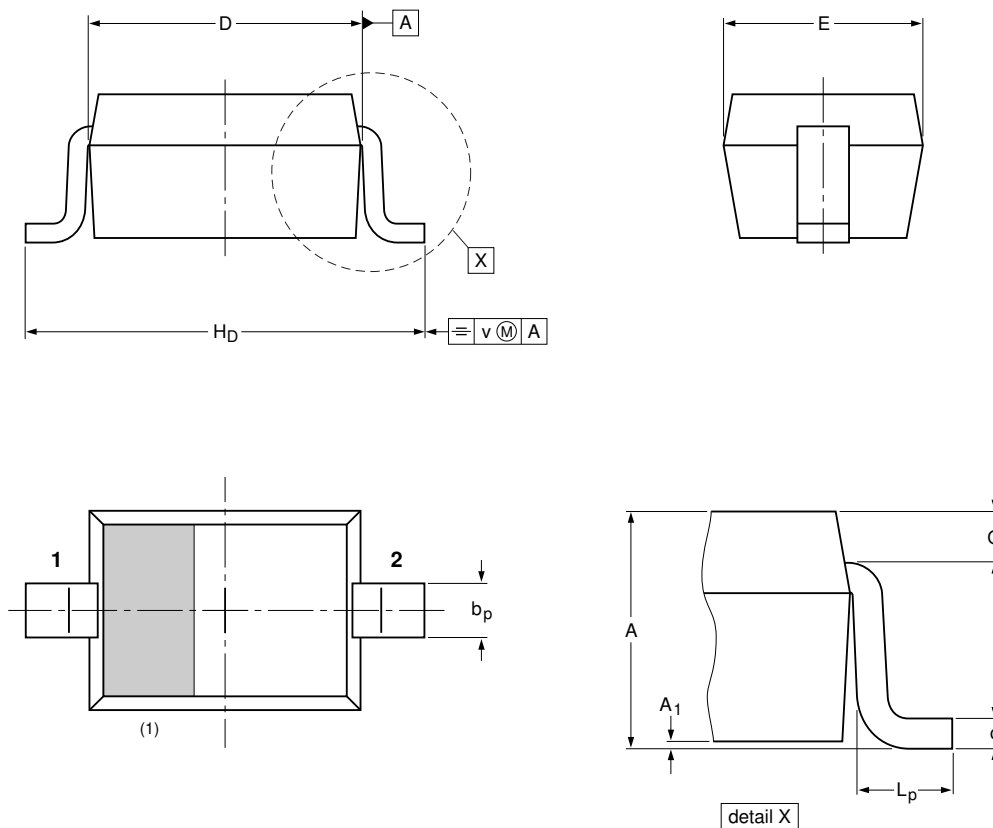
Band-switching diode

BA591

PACKAGE OUTLINE

Plastic surface-mounted package; 2 leads

SOD323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	H _D	L _p	Q	v
mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOD323			SC-76		03-12-17 06-03-16

Band-switching diode

BA591

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Band-switching diode

BA591

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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